

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

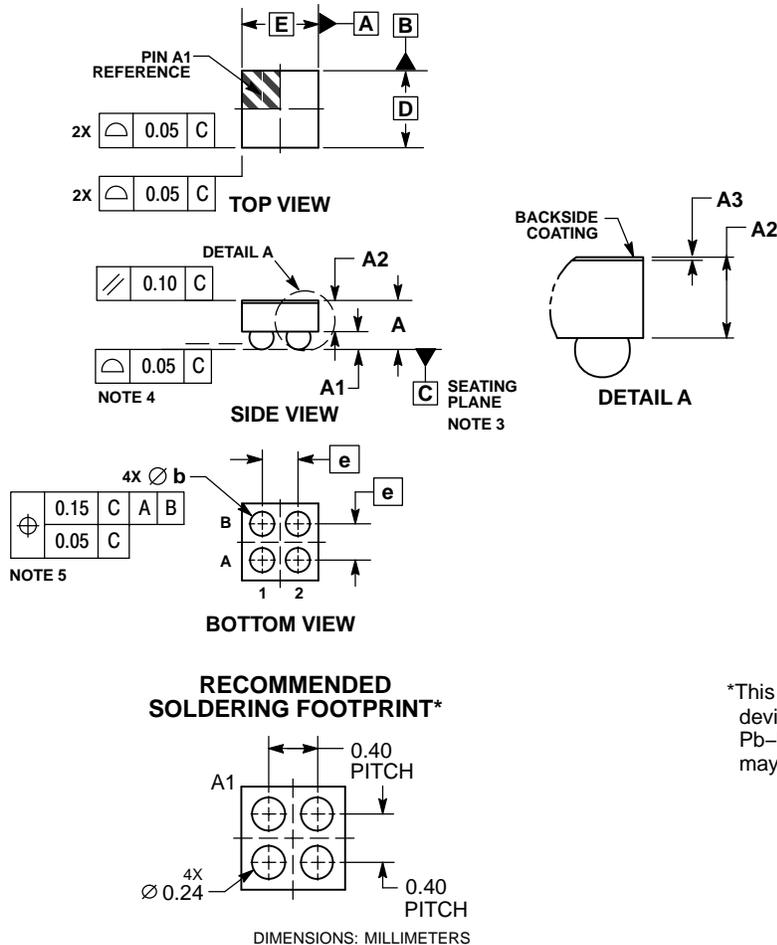
ON Semiconductor®



SCALE 4:1

WLCSP4, 0.84x0.84
CASE 567MN
ISSUE A

DATE 01 SEP 2016

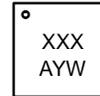


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.60
A1	0.18	0.22
A2	0.34 REF	
A3	0.02 REF	
b	0.24	0.30
D	0.84 BSC	
E	0.84 BSC	
e	0.40 BSC	

GENERIC MARKING DIAGRAM*



A = Assembly Location
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP4, 0.84X0.84	PAGE 1 OF 2

